P. 03

MEGENES

I hereby certify that this correspondence is being transmitted via facsimile to the Commissioner for Patents at (703) 872 9306 on 6 April 2005

APR 9 6 2003

By Lenda Ce Clemena Date Of

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Inventor(s): Kong Weng Lee et al.

Group Art Unit: 2811

Serial No.: 10/608,605

Examiner: Thomas J. Magee

Filed: 27 June 2003

Title: Packaging Device for Semiconductor Die, Semiconductor Device Incorporating Same and

Method of Making Same
Atty Docket: 70030259

AMENDMENT UNDER 37 CFR § 1.116

Commissioner for Patents P.O. Box 1450 Alexandria VA 22313-1450

Sir:

In response to the Official Action dated 9 February 2005, the applicants respectfully request entry of the following amendments:

Rev E Best Available Copy